



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSL606SN H6327	Issued	03. May 2021
MA#	MA000906354		
Package	PG-TSOP6-6-6	Weight*	13.57 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.006	0.04		433	
	noble metal	gold	7440-57-5	0.023	0.17		1678	
	inorganic material	silicon	7440-21-3	0.347	2.56	2.77	25604	27715
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		435	
	non noble metal	chromium	7440-47-3	0.018	0.13		1306	
	non noble metal	copper	7440-50-8	5.882	43.35	43.53	433520	435348
wire	non noble metal	copper	7440-50-8	0.047	0.35	0.35	3501	3501
encapsulation	organic material	carbon black	1333-86-4	0.068	0.50		4984	
	plastics	epoxy resin	-	1.454	10.72		107159	
	inorganic material	silicondioxide	60676-86-0	5.241	38.63	49.85	386270	498413
leadfinish	non noble metal	tin	7440-31-5	0.299	2.20	2.20	22030	22030
plating	noble metal	silver	7440-22-4	0.176	1.30	1.30	12993	12993
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com